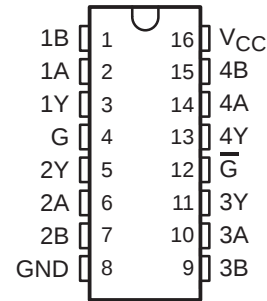


SN75ALS197 QUADRUPLE DIFFERENTIAL LINE RECEIVER

SLLS045B – JANUARY 1989 – REVISED MAY 1995

- Meets or Exceeds the Requirements of ITU Recommendations V.10, V.11, X.26, and X.27
- Designed for Multipoint Bus Transmission on Long Bus Lines in Noisy Environments
- Designed to Operate Up to 20 Mbaud
- 3-State Outputs
- Common-Mode Input Voltage Range – 7 V to 7 V
- Input Sensitivity . . . ± 300 mV
- Input Hysteresis . . . 120 mV Typ
- High-Input Impedance . . . 12 k Ω Min
- Operates from Single 5-V Supply
- Low Supply-Current Requirement 35 mA Max
- Improved Speed and Power Consumption Compared to AM26LS32A

D OR N PACKAGE
(TOP VIEW)



description

The SN75ALS197 is a monolithic, quadruple line receiver with 3-state outputs designed using advanced, low-power, Schottky technology. This technology provides combined improvements in bar design, tooling production, and wafer fabrication. This, in turn, provides significantly lower power requirements and permits much higher data throughput than other designs. The device meets the specifications of ITU Recommendations V.10, V.11, X.26, and X.27. It features 3-state outputs that permit direct connection to a bus-organized system with a fail-safe design that ensures the outputs will always be high if the inputs are open.

The device is optimized for balanced, multipoint bus transmission at rates up to 20 megabits per second. The input features high-input impedance, input hysteresis for increased noise immunity, and an input sensitivity of ± 300 mV over a common-mode input voltage range of –7 V to 7 V. It also features active-high and active-low enable functions that are common to the four channels. The SN75ALS197 is designed for optimum performance when used with the SN75ALS192 quadruple differential line driver.

The SN75ALS197 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE
(each receiver)

DIFFERENTIAL INPUTS A – B	ENABLES		OUTPUT Y
	G	$\overline{G}$	
$V_{ID} \geq 0.3$ V	H	X	H
	X	L	H
-0.3 V < V_{ID} < 0.3 V	H	X	?
	X	L	?
$V_{ID} \leq -0.3$ V	H	X	L
	X	L	L
X	L	H	Z
Open	H	X	H
	X	L	H

H = high level, L = low level, X = irrelevant, ? = indeterminate, Z = high impedance (off)



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

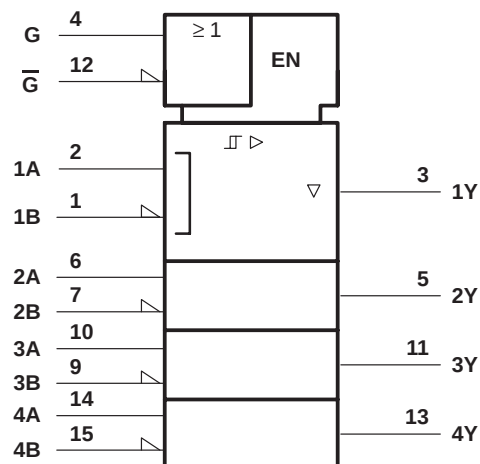
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SN75ALS197 QUADRUPLE DIFFERENTIAL LINE RECEIVER

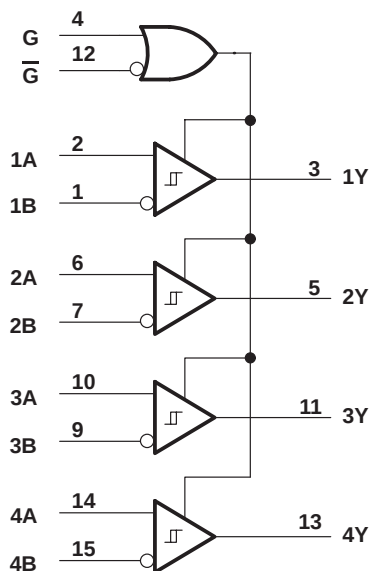
SLLS045B – JANUARY 1989 – REVISED MAY 1995

logic symbol†

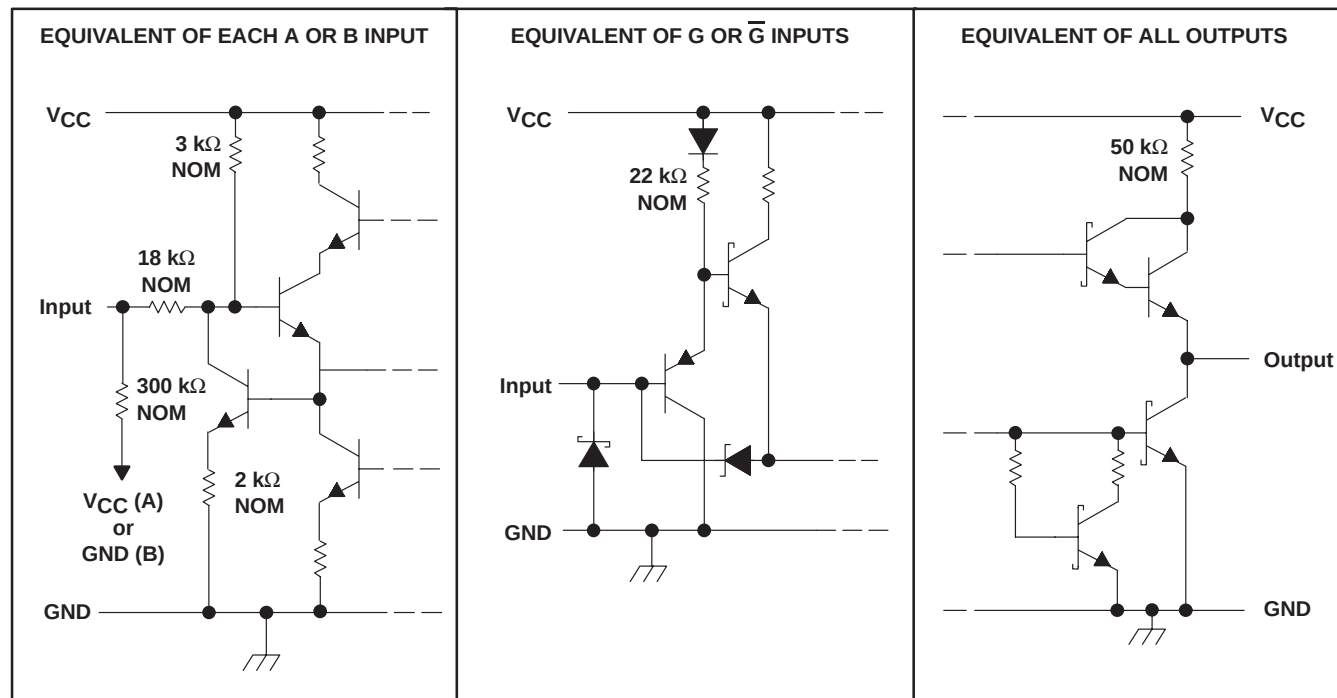


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage, V_I (A or B inputs)	± 15 V
Differential input voltage, V_{ID} (see Note 2)	± 15 V
Enable input voltage, V_I	7 V
Low-level output current, I_{OL}	50 mA
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range, T_{stg}	– 65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential input voltage, are with respect to network ground terminal.
2. Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR	$T_A = 70^\circ\text{C}$ POWER RATING
D	950 mW	7.6 mW/°C	608 mW
N	1150 mW	9.2 mW/°C	736 mW

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	4.75	5	5.25	V
Common-mode input voltage, V_{IC}			± 7	V
Differential input voltage, V_{ID}			± 12	V
High-level input voltage, V_{IH}	2			V
Low-level input voltage, V_{IL}			0.8	V
High-level output current, I_{OH}			–400	μA
Low-level output current, I_{OL}			16	mA
Operating free-air temperature, T_A	0		70	°C

SN75ALS197

QUADRUPLE DIFFERENTIAL LINE RECEIVER

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electrical characteristics over recommended range of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V_{IT+} Positive-going input threshold voltage				300	mV
V_{IT-} Negative-going input threshold voltage		-300 [‡]			mV
V_{hys} Hysteresis voltage ($V_{IT+} - V_{IT-}$)	See Figure 4		120		mV
V_{IK} Enable-input clamp voltage	$I_I = -18$ mA			-1.5	V
V_{OH} High-level output voltage	$V_{ID} = 300$ mV, $I_{OH} = -400$ μ A	2.7	3.6		V
V_{OL} Low-level output voltage	$V_{ID} = -300$ mV			0.45	V
				0.5	
I_{OZ} High-impedance-state output current	$V_{CC} = 5.25$ V			20	μ A
				-20	
I_I Line input current	Other input at 0 V, See Note 3			0.7	mA
				-1.0	
I_H High-level enable-input current				20	μ A
				100	
I_{IL} Low-level enable-input current	$V_{IL} = 0.4$ V			-100	μ A
	Input resistance	12	18		k Ω
I_{OS} Short-circuit output current [§]	$V_{ID} = 3$ V, $V_O = 0$	-15	-78	-130	mA
I_{CC} Supply current	Outputs disabled		22	35	mA

[†] All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

[‡] The algebraic convention, in which the less positive limit is designated minimum, is used in this data sheet for threshold voltage levels only.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 3: Refer to ANSI Standard EIA/TIA-422-B and EIA/TIA-423-B for exact conditions.

switching characteristics, $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} Propagation delay time, low- to high-level output	$V_{ID} = -2.5$ V to 2.5 V, $C_L = 15$ pF,	15	22		ns
t_{PHL} Propagation delay time, high- to low-level output	See Figure 2	15	22		ns
t_{PZH} Output enable time to high level	$C_L = 15$ pF, See Figure 3	13	25		ns
t_{PZL} Output enable time to low level		11	25		
t_{PHZ} Output disable time from high level	$C_L = 15$ pF, See Figure 3	13	25		ns
t_{PLZ} Output disable time from low level		15	22		

PARAMETER MEASUREMENT INFORMATION

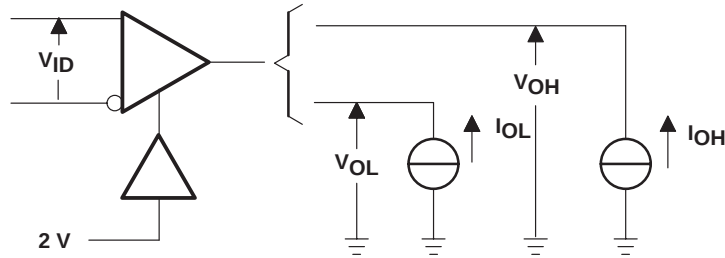
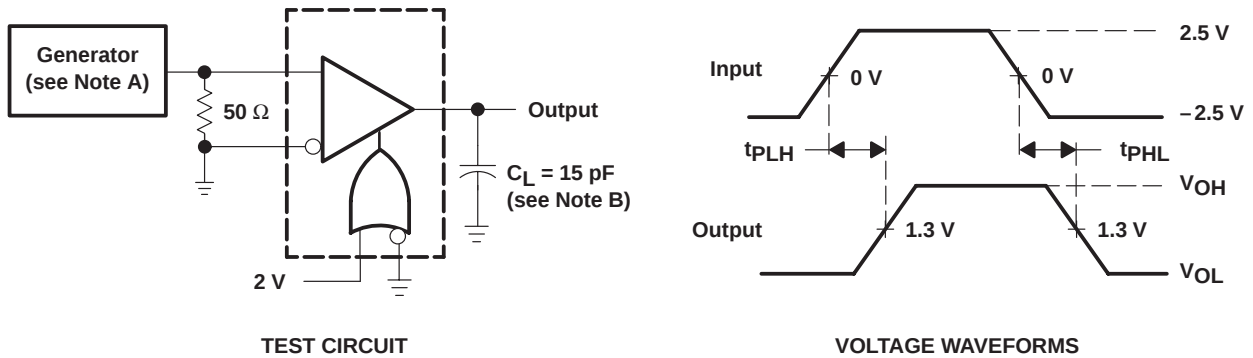


Figure 1. V_{OH} and V_{OL} Test Circuit



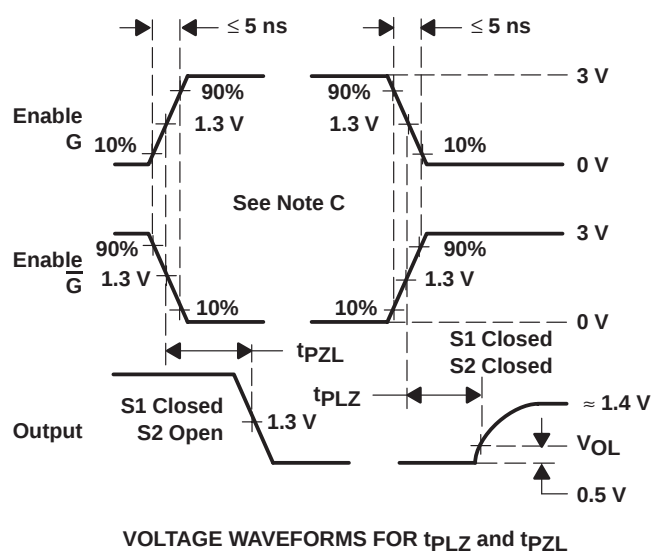
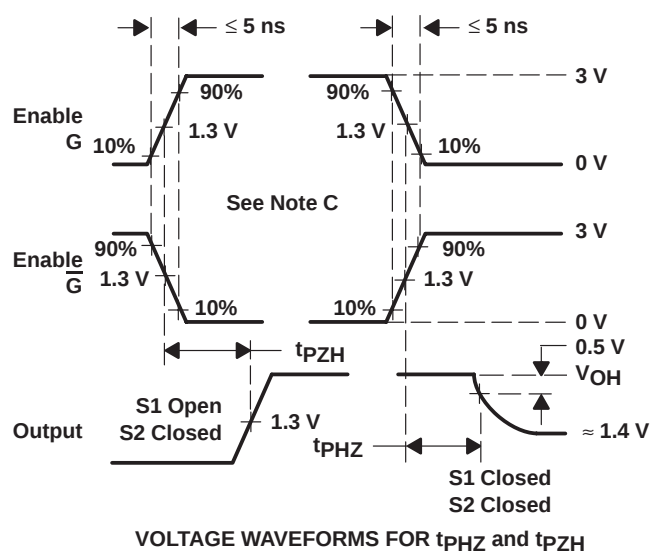
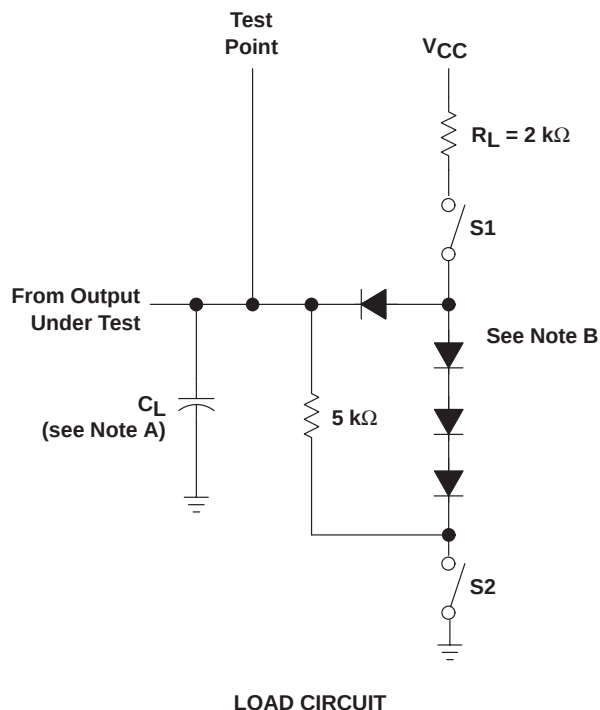
- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1 \text{ MHz}$, duty cycle $\leq 50\%$, $Z_O = 50 \Omega$, $t_r \leq 6 \text{ ns}$, $t_f \leq 6 \text{ ns}$.
B. C_L includes probe and jig capacitance.

Figure 2. t_{PLH} and t_{PHL} Test Circuit and Voltage Waveforms

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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
B. All diodes are 1N3064 or equivalent.
C. Enable G is tested with G high; $\bar{G}$ is tested with G low.

Figure 3. t_{pHZ} , t_{pZH} , t_{pLZ} , and t_{pZL} Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

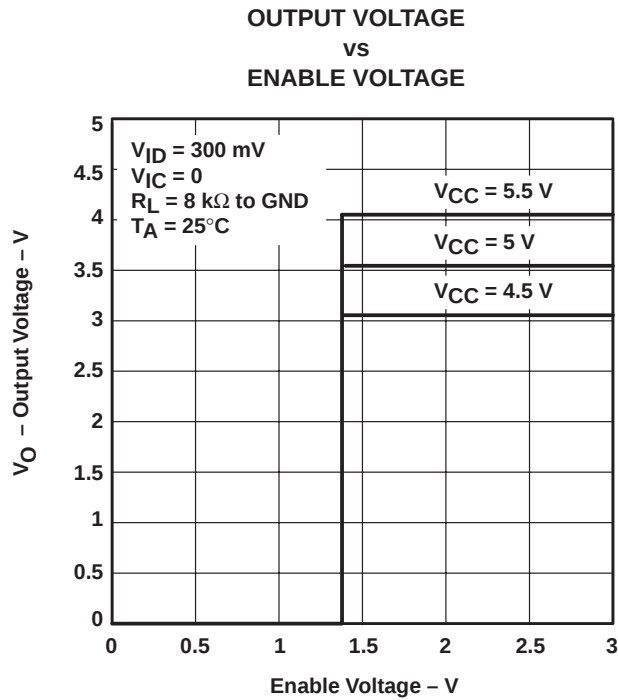


Figure 4

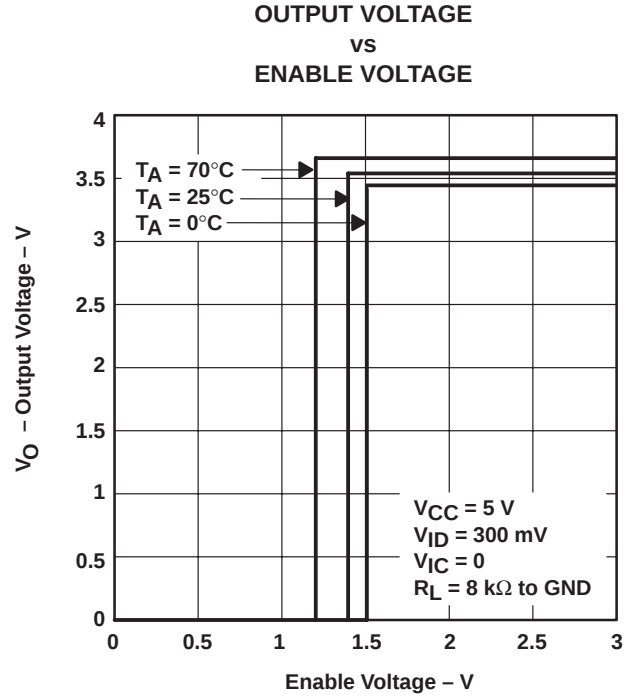


Figure 5

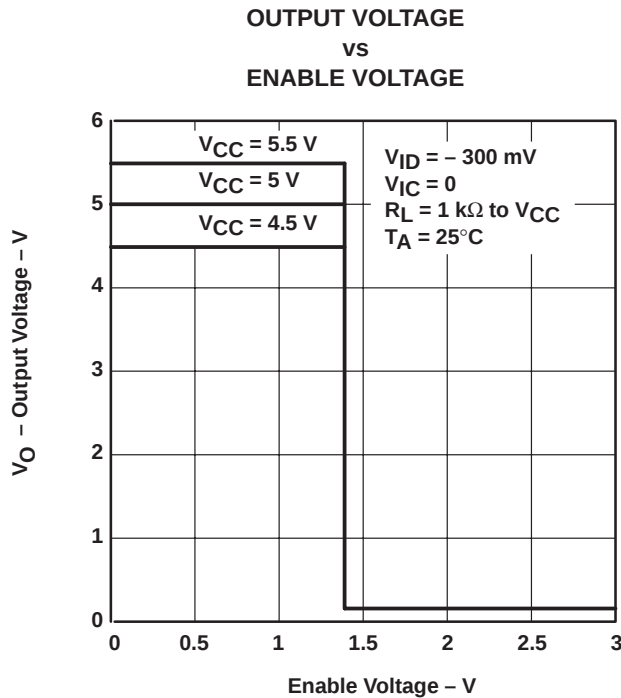


Figure 6

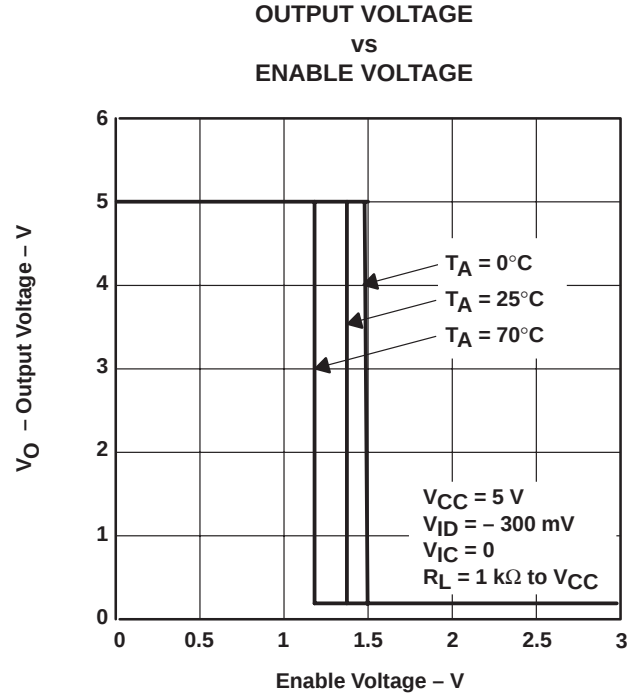


Figure 7

SN75ALS197
QUADRUPLE DIFFERENTIAL LINE RECEIVER

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TYPICAL CHARACTERISTICS

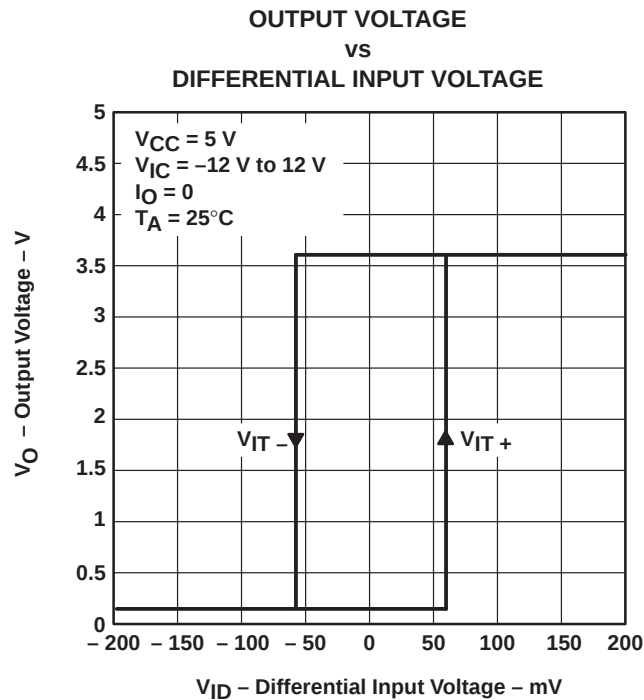


Figure 8

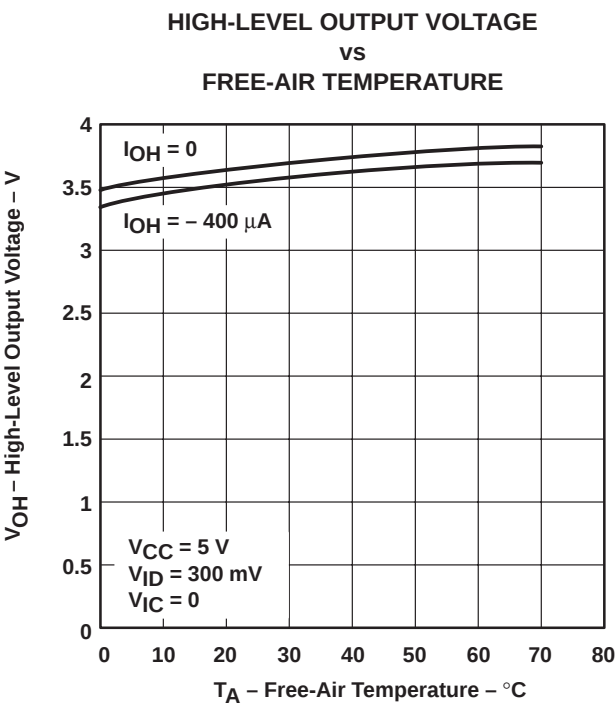


Figure 9

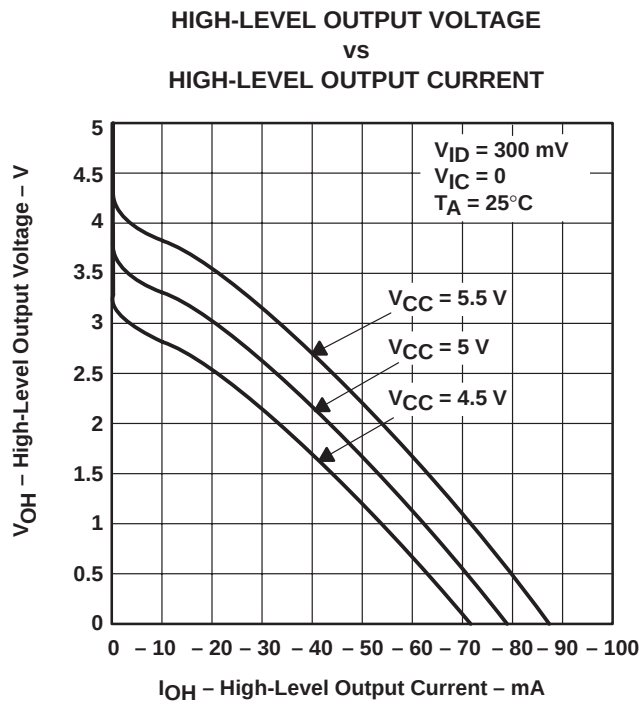


Figure 10

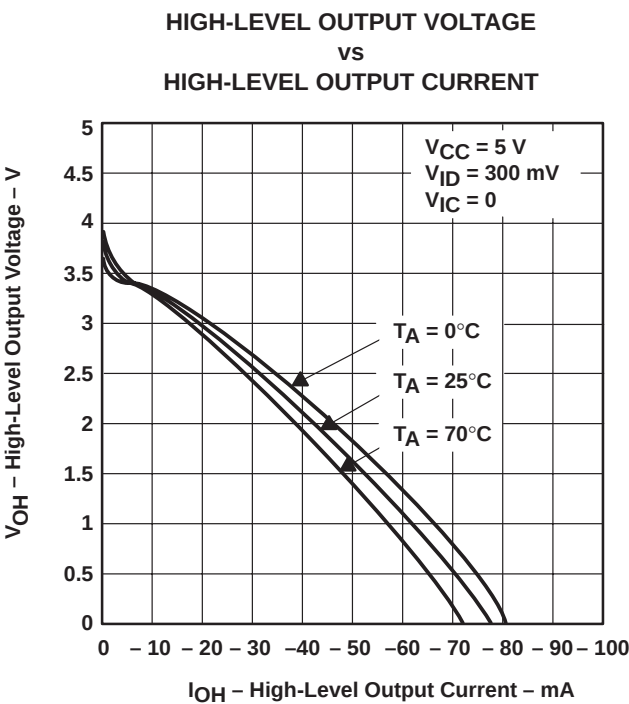


Figure 11

TYPICAL CHARACTERISTICS

LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

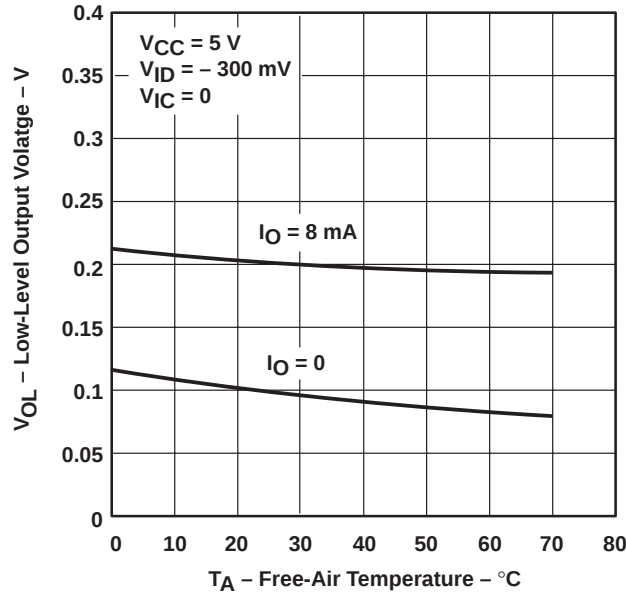


Figure 12

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

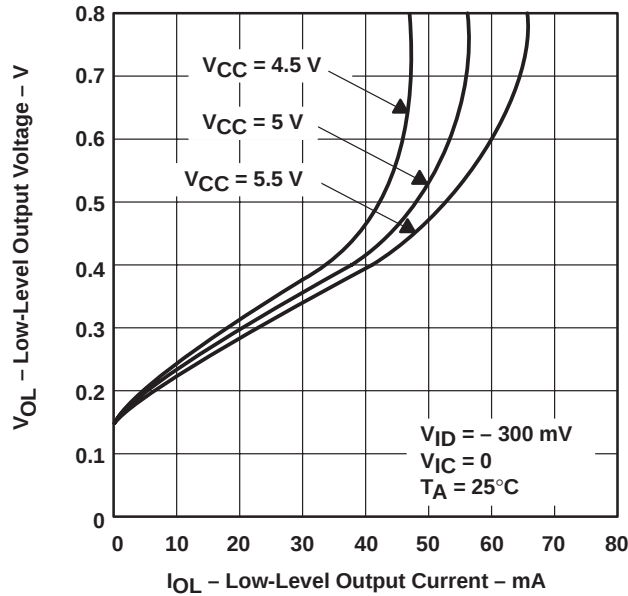


Figure 13

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

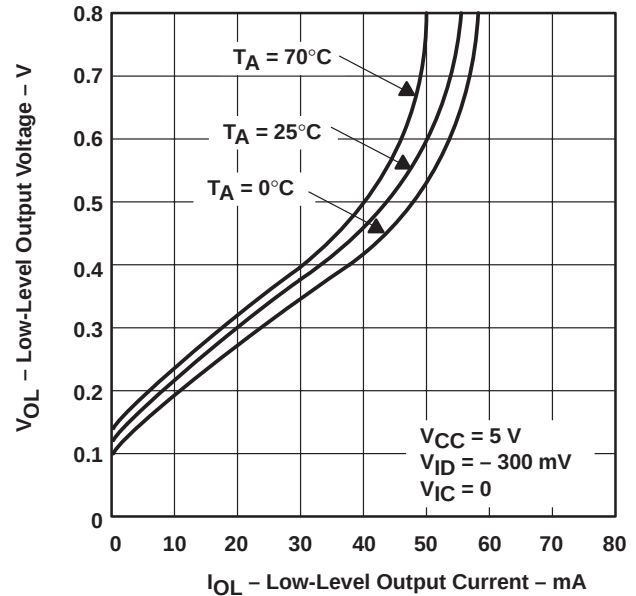


Figure 14

SN75ALS197 QUADRUPLE DIFFERENTIAL LINE RECEIVER

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TYPICAL CHARACTERISTICS

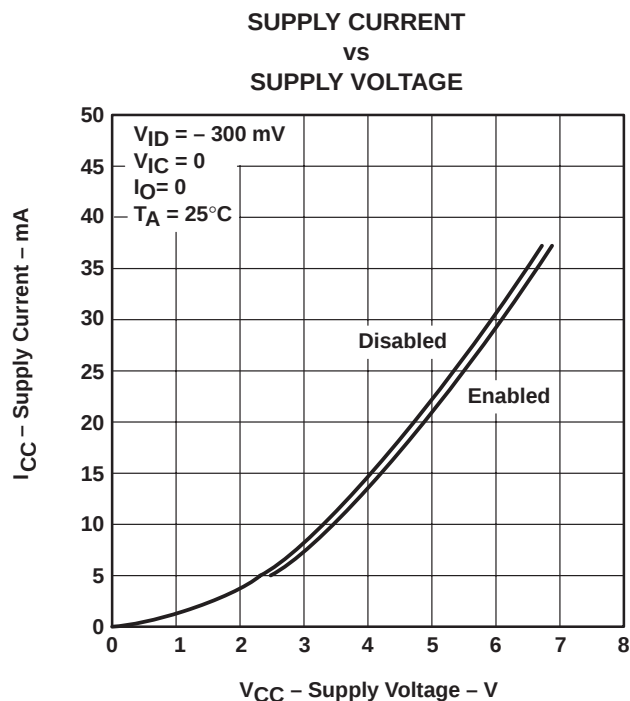


Figure 15

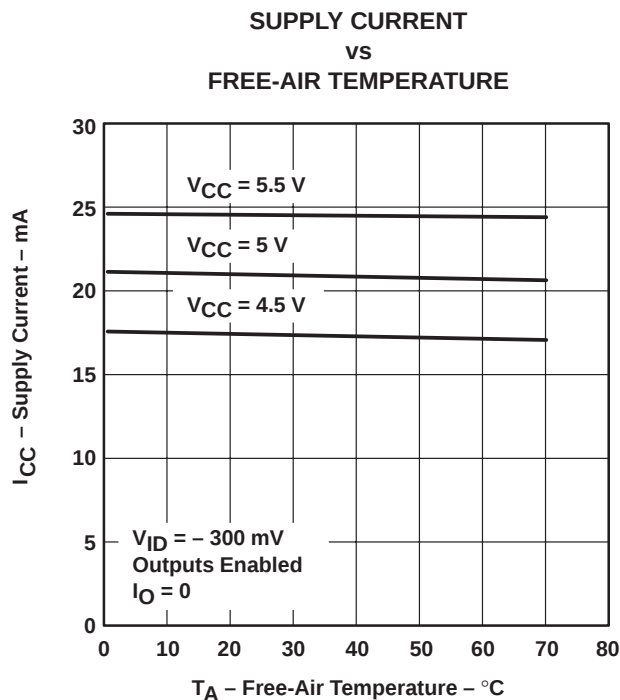


Figure 16

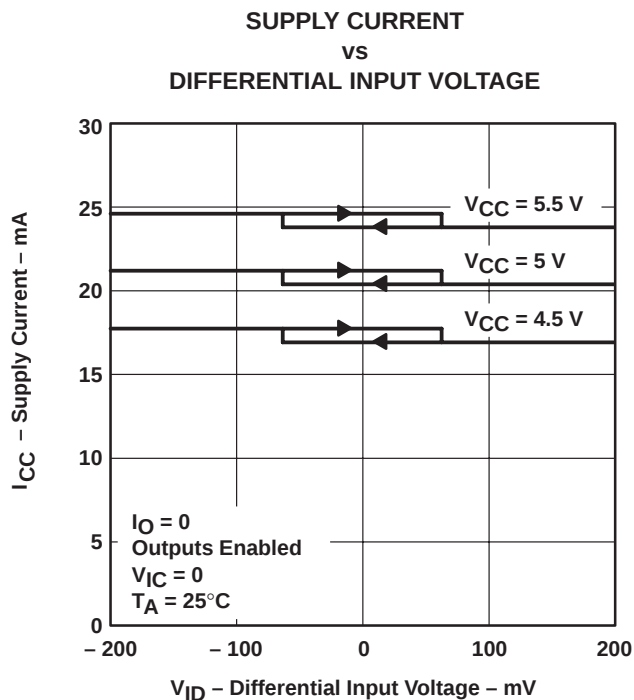


Figure 17

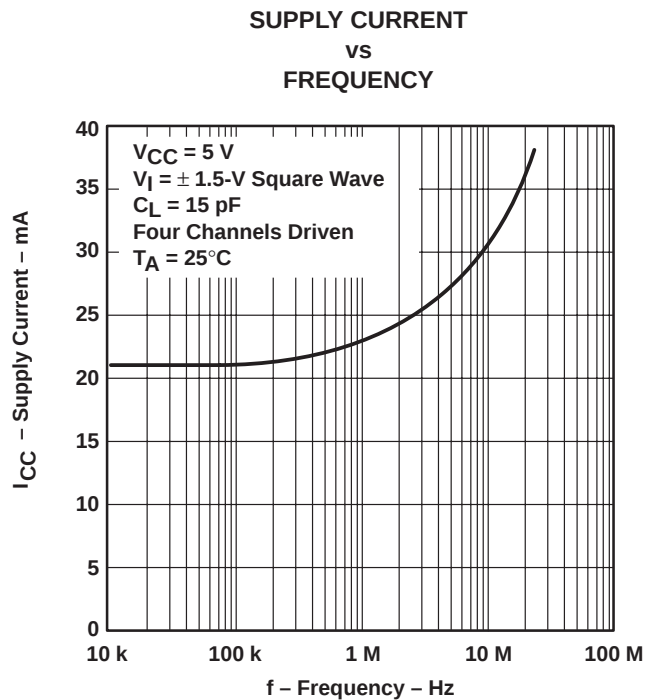


Figure 18

TYPICAL CHARACTERISTICS

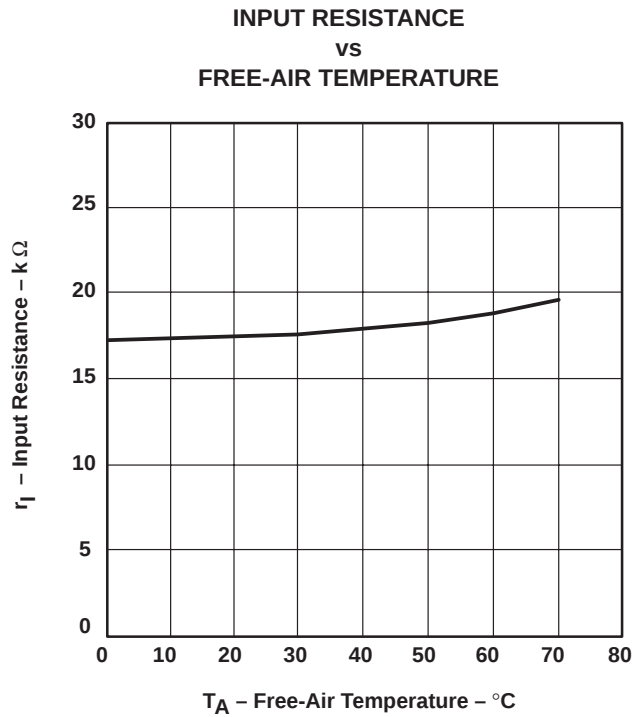


Figure 19

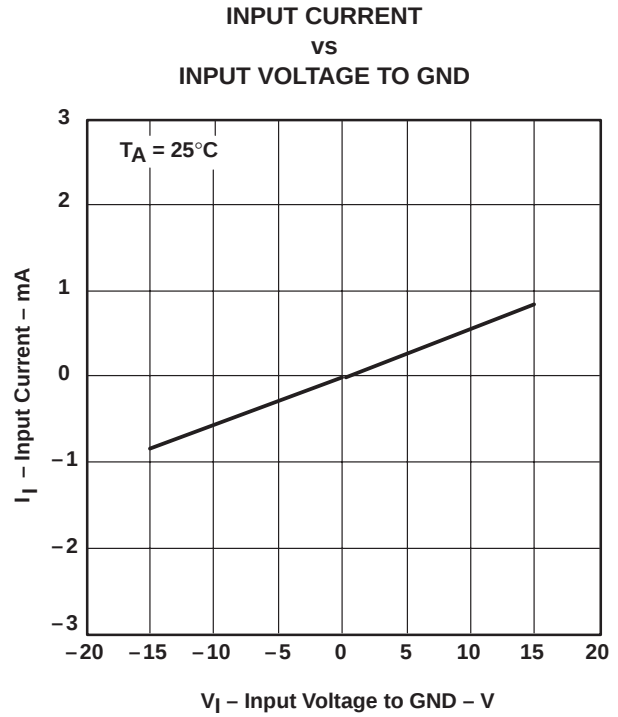


Figure 20

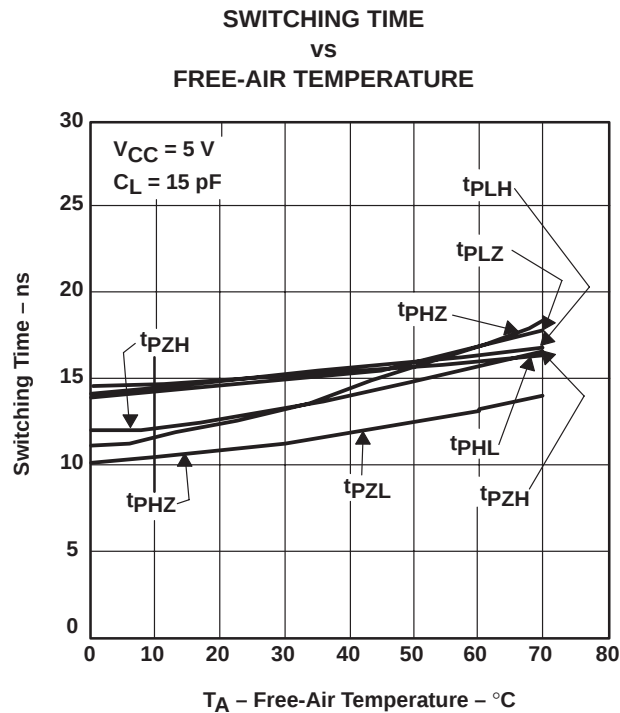


Figure 21

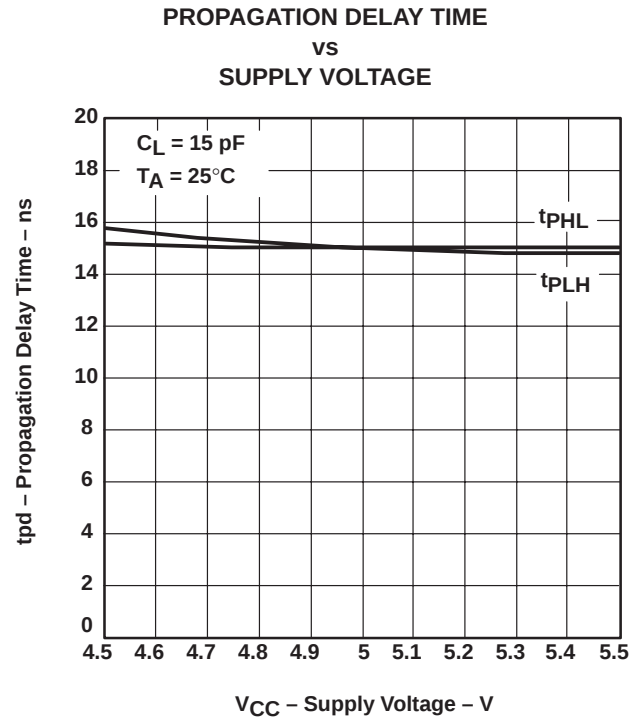


Figure 22

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75ALS197D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS197DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS197DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS197DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS197DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS197DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS197J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN75ALS197N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS197NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS197NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS197NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS197NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS197DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN75ALS197NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS197DR	SOIC	D	16	2500	333.2	345.9	28.6
SN75ALS197NSR	SO	NS	16	2000	367.0	367.0	38.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



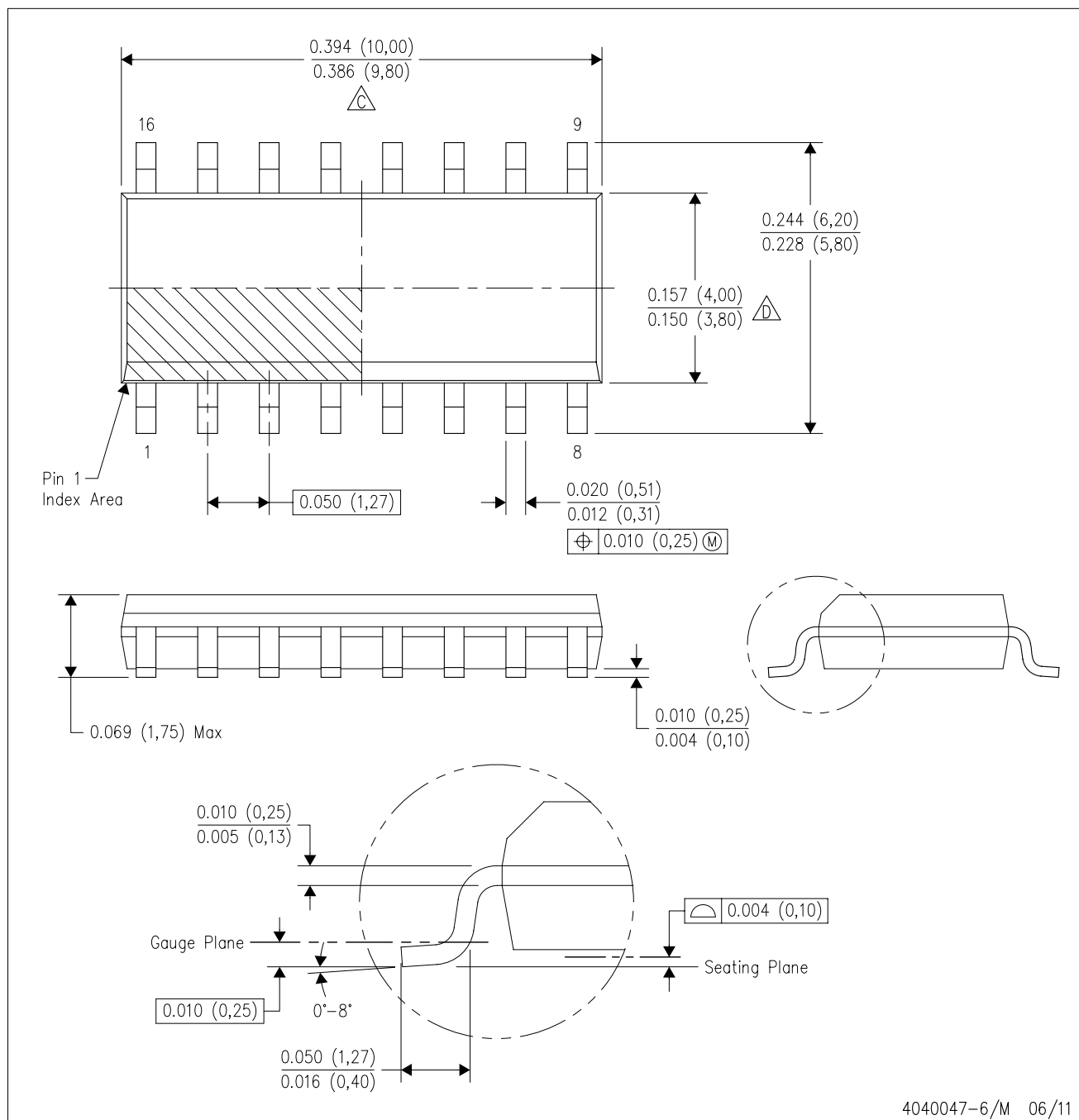
4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



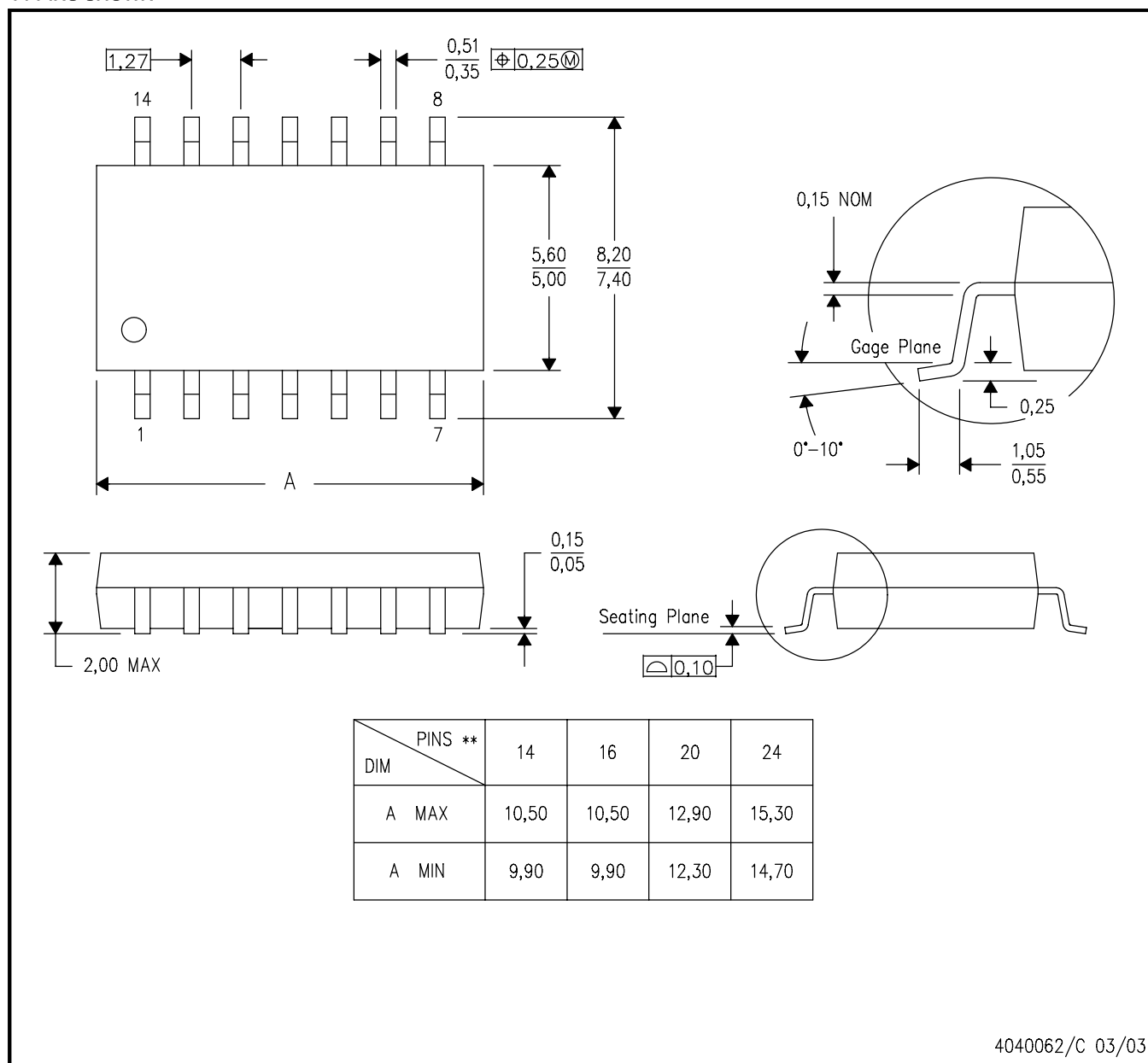
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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